

WBF4009
Water Based Liquid Flux

Product Description

WBF4009 is a water-based, no-clean flux designed for mass production in leaded and lead free application. This flux has no halide in its activator system, hence, reduces the possibility of corrosion and short circuits due to the presence of active ions. WBF4009 is finely tuned to offer shiny solder connection and the best solderability in electronic assemblies.

Application

WBF4009 is specially formulated for spraying process. For spraying applications, recommended onboard preheat temperature is about 100 - 130°C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any aqueous flux cleaner available in the market

Recommended Solvent

WBF4009 does not require any solvent.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Store the flux at temperature of 4°C to 30°C under shade and avoid direct exposure to sunlight, WBF4009 can be stored for up to 6 months.

Packaging

Available in 20kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Transparent
Specific Gravity @ 25°C	1.003 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 3hrs)	2.90 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	28.5 +/- 2 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ORM0
<small>IPC J-STD-004</small>	
Spread Factor	> 80% (SnPb) > 70% (SCS7)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Shiny

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